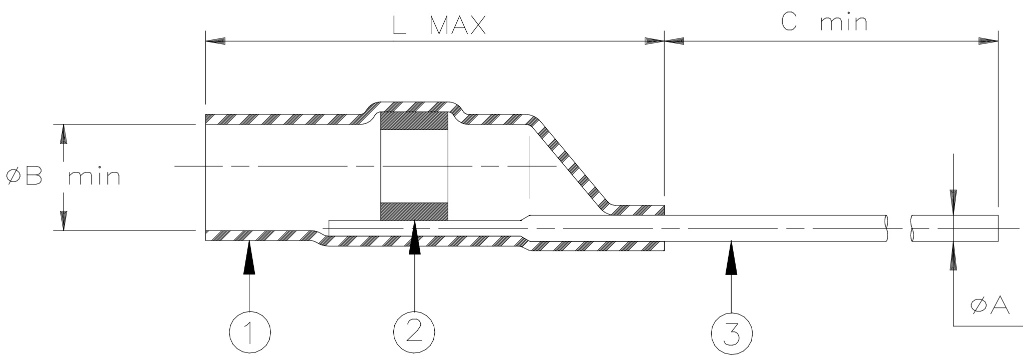
CUSTOMER DRAWING



Product Name	Product Dimensions				Wire Dimensions		
	øA max	øB min	C min	L max	D max	S ±0.2	Size AWG
B-801-16	0.68	2.55	10	13.8	2.55	5	20 - 24
B-801-18	0.88	2.55	10	13.2	2.55	5	20 -24
B-801-19	1.08	1.90	8	11.1	1.90	5	22 - 26
B-801-46	0.68	1.90	12	9.2	1.90	4	22 - 26
B-801-48	0.88	1.90	12	9.2	1.90	4	22 - 26

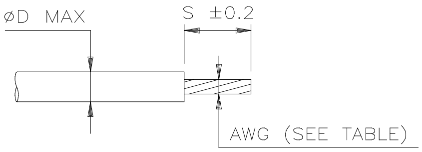
MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
   SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.
   FLUX: TYPE ROL0 per ANSI-J-STD-004.
3. PIN: Cu/Sn-Pb/5b per ASTM B-579-73.

APPLICATION

1. These controlled soldering devices are designed for use in attaching a stranded wire, having tin or silver plated conductors, insulations rated for at least 125°C and meeting the dimensional criteria listed, to a printed circuit board having plated-thru holes with a diameter 0.3 to 0.6 larger than the lead diameter (A).
2. To install part, strip wire (S). Position sleeve so that the solder preform is over conductor and the pre-installed lead does not overlap wire insulation. Heat, using a suitable heat source and reflector until the solder preform melts and flows to form a fillet between the two wires.
3. When installed as above, assembly will meet requirements of Raychem Specification RT-1404 for splices.

For best results, prepare the wire as shown:



Raychem
THERMOFIT
DEVICES

TITLE:
PINPAK*
PCB TERMINATOR

Unless otherwise specified dimensions are in millimeters.

DOCUMENT NO.:
B-801-1X, B-801-4X

TOLERANCES:
0.00 N/A
0.0 N/A
0 N/A

ANGLES: N/A
ROUGHNESS IN MICRON

TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.

REV: 4
DATE: 09-Mar-2020

DRAWN BY: M. FORONDA
DATE: 22-Mar-1999
ECO: ECO-20-003687
SCALE: NTS
SIZE: A
SHEET: 1 of 1